

### Features & Benefits

- \* Mechanical compatibility with direct mounting of the COB products to the LED thermal body and thermal performance matching the lumen packages.
- \* For Down light designs from 800 to 1200 lumen.
- \* Thermal resistance range  $R_{th}$  2.75°C/W.
- \* Full accessory kit with LED cooler Body, PSU mounting shrapnel & lens holder.
- \* Other accessories like COB holder & lens separate available.
- \* Modular design with mounting holes foreseen for direct mounting of a wide range of LED modules and COB's.
- \* Forged from highly conductive aluminum (ADC12).
- \* Dimension 90x90mm - Standard height 90mm, Other heights on request.
- \* 3 standard colors - white powder, black powder and gray powder.



Cover



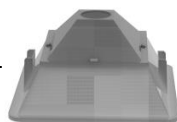
Heatsink



Holder



PC Reflector



- 01) Bridelux: Vero 10 Vero SE 10 LED engines;
- 02) Cree: XLamp CXA 13xx, XLamp CXB 15xx Series engines;
- 03) Citizen: CLU026, CLU027, CLU028, CLU721, CLU711, CLU701 LED engines;
- 04) Edison: EdiLex III COB LED engines;
- 05) GE lighting: Infusion™ LED engines;
- 06) LG Innotek: 7W, 10W LED engines;
- 07) LumiLEDs: LUXEON 1202/1203 LED engines;
- 08) Lumens: Ergon-COB 1304, 15xx LED engines;
- 09) Luminus: CXM-6, CHM/CLM/CXM-9 LED engines;
- 10) Nichia: NVxxx024Z, NVxxx036Z, NFCWxxxB Series LED engines;
- 11) Osram: SOLERIQ® S9 LED engines;
- 12) Philips: Fortimo SLM LED engines;
- 13) Prolight Opto: PACJ-7xxx/14xxx/21xxx/28xxx-xxxx engines;
- 14) Samsung: LCxxxC Series, LCxxxD Series LED engines;
- 15) Seoul Semiconductor: SAWxxxxxx Series, DC COB LED engines;
- 16) Tridonic: SLE G5, SLE G6 LES10mm LED engines;
- 17) Vossloh-Schwabe: LUGA Shop and LUGA C LED engines;

### Order Information

Example: Cube-90-WH

Cube - **1** - **2**

**1**

Product model  
- 90

**2**



Finish  
- WH White  
- BK Black  
- GY Gray

#### Notes:

- Mentioned models are an extraction of full product range.
- For specific mechanical adaptations please contact MingfaTech.
- MingfaTech reserves the right to change products or specifications without prior notice.



## The product data table

	 <i>Cube</i>
<b>Model No.</b>	<b>Cube-90</b>
<b>Heatsink Size</b>	<b>90x90x90mm</b>
<b>Heatsink Material</b>	<b>ADC12</b>
<b>Heatsink Finish</b>	<b>White/Black/Gray</b>
<b>Weight</b>	<b>303g</b>
<b>Dissipated power</b> (Ths-amb,50°C)	<b>10 (W)</b>
<b>Beam Angle</b>	<b>50°</b>
<b>Thermal Resistance</b> (Rhs-amb)	<b>2.75(°C/W)</b>

\* 3D files are available in ParaSolid, STP and IGS on request

\* The thermal resistance  $R_{th}$  is determined with a calibrated heat source of 14mm×14mm central placed on the heat sink,  $T_{amb}$  40° and an open environment. Reference data @ heat sink to ambient temperature rise  $T_{hs-amb}$  50°C

The thermal resistance of a LED cooler is not a fix value and will vary with the applied dissipated power  $P_d$

\* Dissipated power  $P_d$ . Reference data @ heat sink to ambient temperature rise  $T_{hs-amb}$  50°C

The maximal dissipated power needs to be verified in function of required case temperature  $T_c$  or junction temperature  $T_j$  and related to the estimated ambient temperature where the light fixture will be placed  
Please be aware the dissipated power  $P_d$  is not the same as the electrical power  $P_e$  of a LED module

To calculate the dissipated power please use the following formula:  $P_d = P_e \times (1 - \eta_L)$

$P_d$  - Dissipated power

$P_e$  - Electrical power

$\eta_L$  = Light efficiency of the LED module

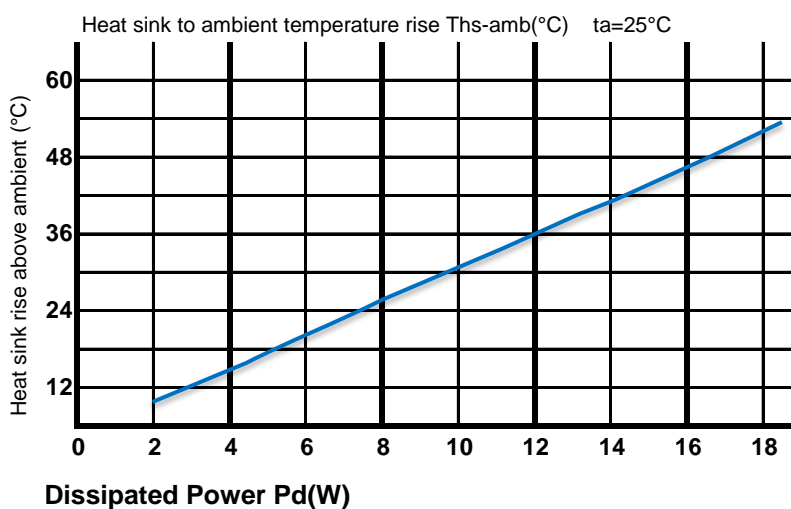


*Cube*

## Cube-90 Lighting Kits assembly & introduction

### The thermal data table

Dissipated Power Pd(W)	Pd=Pe x (1-ηL)	Heat sink to ambient thermal resistance Rhs-amb(°C/W)	Heat sink to ambient temperature rise Ths-amb(°C)
		Cube-90	
	2	3.35	7.1
	5	3.00	16
	8	2.83	24.2
	10	2.75	29.5
	12	2.68	34.5
	15	2.61	42.2
	20	2.53	54.5



\* Please be aware the dissipated power Pd is not the same as the electrical power Pe of a LED module.

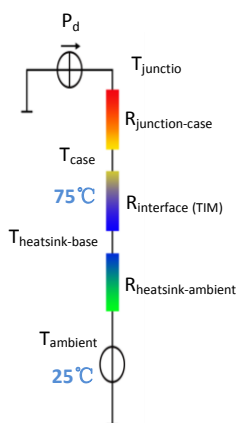
\*To calculate the dissipated power please use the following formula:  $P_d = P_e \times (1 - \eta_L)$ .

Pd - Dissipated power ; Pe - Electrical power ;  $\eta_L$  = Light efficiency of the LED module;

\*The aluminum substrate side of the package outer shell is thermally connected to the heat sink via TIM (Thermal interface material).

MingFa recommends the use of a high thermal conductive interface between the LED module and the LED cooler.

Either thermal grease, A thermal pad or a phase change thermal pad thickness 0.1-0.15mm is recommended.



\*Thermal resistance is a heat property and a measurement of a temperature difference by which an object or material resists a heat flow.

Geometric shapes are different, the thermal resistance is different. Formula:  $\theta = (T_{hs} - T_a) / P_d$

$\theta$  - Thermal Resistance [ $^{\circ}\text{C}/\text{W}$ ];  $T_{hs}$  - Heatsink temperature ;  $T_a$  - Ambient temperature ;

\*The thermal resistance between the junction section of the light-emitting diode and the aluminum substrate side of the package outer shell is  $R_{\text{junction-case}}$ , the thermal resistance of the TIM outside the package is  $R_{\text{interface (TIM)}}$  [ $^{\circ}\text{C}/\text{W}$ ], the thermal resistance with the heat sink is  $R_{\text{heatsink-ambient}}$  [ $^{\circ}\text{C}/\text{W}$ ], and the ambient temperature is  $T_{\text{ambient}}$  [ $^{\circ}\text{C}$ ].

\*Thermal resistances outside the package  $R_{\text{interface (TIM)}}$  and  $R_{\text{heatsink-ambient}}$  can be integrated into the thermal resistance  $R_{\text{case-ambient}}$  at this point. Thus, the following formula is also used:

$$T_{\text{junction}} = (R_{\text{junction-case}} + R_{\text{case-ambient}}) \cdot P_d + T_{\text{ambient}}$$